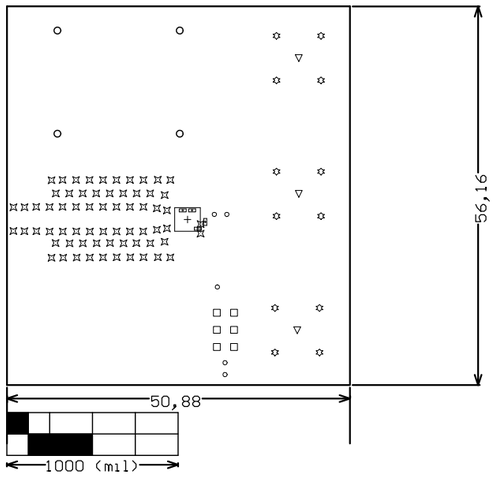
Symbol	Hit Count	Tool Size	Plated	Hole Type
⌑	66	11.811mil (0.3mm)	PTH	Round
□	6	35.433mil (0.9mm)	PTH	Round
▽	3	51.181mil (1.3mm)	PTH	Round
○	4	70.866mil (1.8mm)	PTH	Round
☼	12	86.614mil (2.2mm)	PTH	Round
	91 Total			

+				
◇				
⊠				
×				



M2 Board Dimensions

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcdDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M12 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM	TEXAS INSTRUMENTS	

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MODIFIED BY:	LAYOUT BY:
KRYPTON SOLUTION	
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

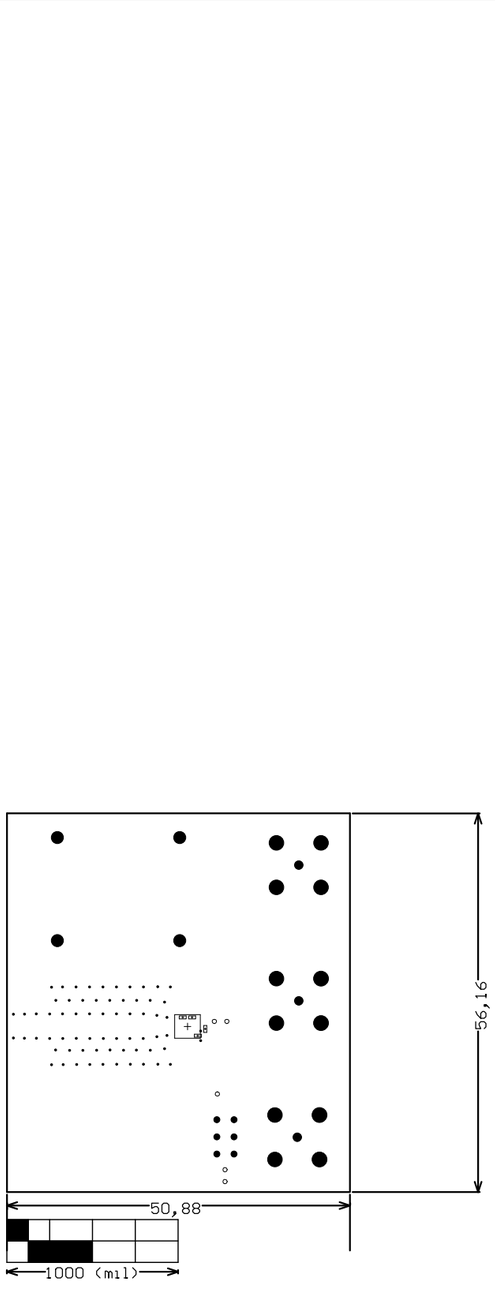
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK



M2 Board Dimensions

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcdDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M2 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM	TEXAS INSTRUMENTS	

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MODIFIED BY:	LAYOUT BY:
KRYPTON SOLUTION	
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

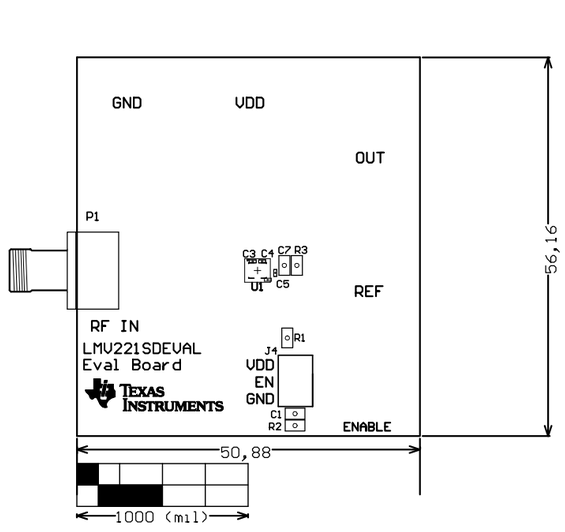
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK



M2 Board Dimensions

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcdDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M12 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM	TEXAS INSTRUMENTS	

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MODIFIED BY:	LAYOUT BY:
KRYPTON SOLUTION	
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

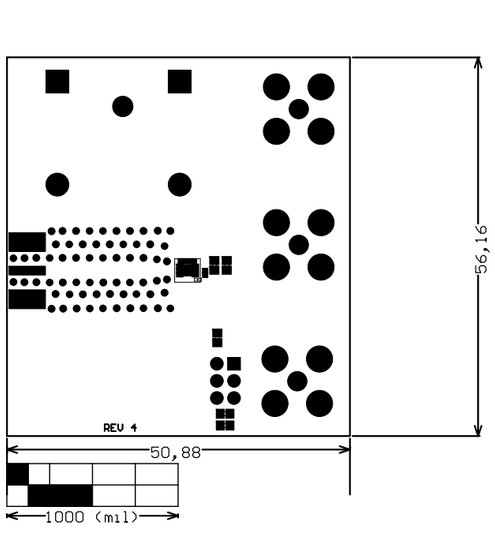
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK



M2 Board Dimensions

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M2 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM	TEXAS INSTRUMENTS	

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MODIFIED BY:	LAYOUT BY:
KRYPTON SOLUTION	
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

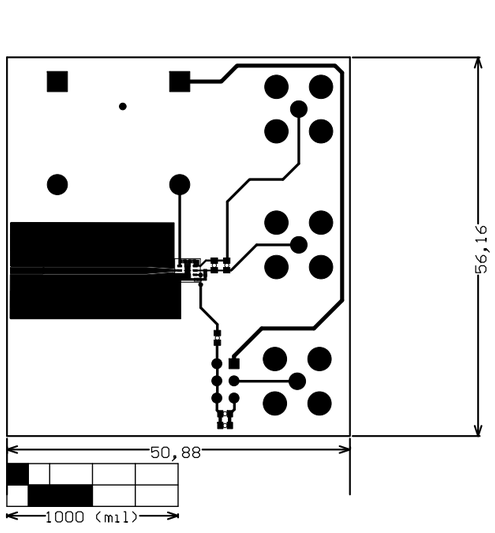
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK



M2 Board Dimensions

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M2 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM	TEXAS INSTRUMENTS	

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MODIFIED BY:	LAYOUT BY:
KRYPTON SOLUTION	
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

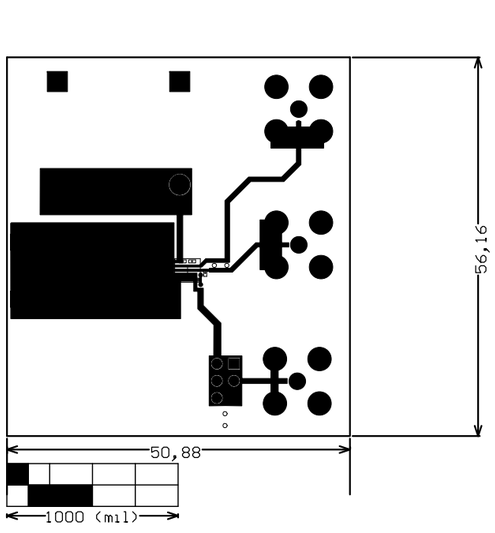
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK



M2 Board Dimensions

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M2 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM		TEXAS INSTRUMENTS

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MODIFIED BY: KRYPTON SOLUTION	LAYOUT BY:
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

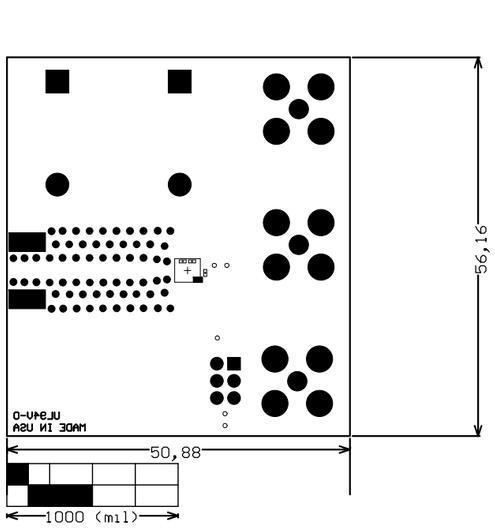
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK



M2 Board Dimensions

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcdDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M12 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM		TEXAS INSTRUMENTS

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MODIFIED BY:	LAYOUT BY:
KRYPTON SOLUTION	
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: LMV221SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2211Mil X 2003Mil

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 18 MIL
MIN. VIA PAD SIZE: 23 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
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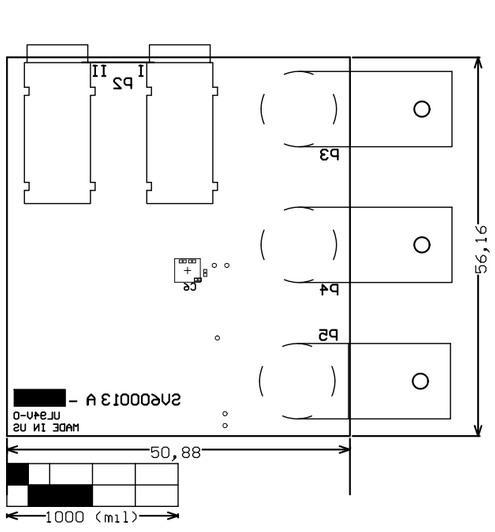
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [ ] METAL [X] SILK



M2 Board Dimensions

TEXAS INSTRUMENTS

PROJECT TITLE: LMV221 EVALUATION BOARD
DESIGNED FOR: Public Release
FILE NAME: LMV221EVAL.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600013	REV: A	
LAYER NAME = M2 Top Layer			
PLOT NAME = LMV221SDEVAL.GM11	GENERATED : 6/23/2013 5:06:36 PM		TEXAS INSTRUMENTS

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MODIFIED BY: KRYPTON SOLUTION	LAYOUT BY:
SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009